
IBM Power[®] System S822LC (8335-GTB) Quick Install Guide

Read all precautions and instructions before you start working on the system and its parts.

Use normal electrostatic discharge (ESD) procedures when working on the system and parts. IBM recommends wearing gloves and an ESD wrist strap to avoid possible damage to the equipment.

The information about the 8335-GTB system is available online in the IBM Knowledge Center.
<https://ibm.biz/QR8335-GCB>

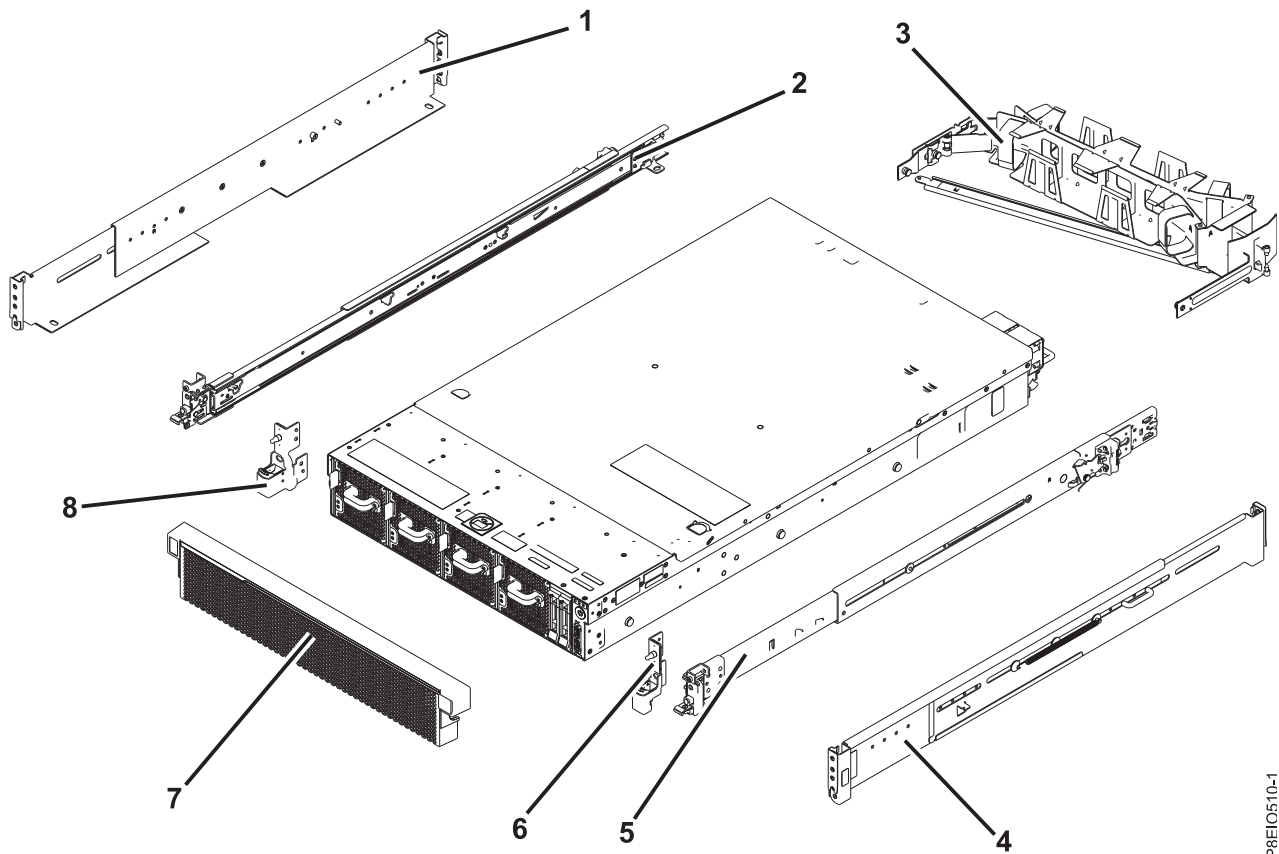


8335-GTB parts

Use this information to find the field-replaceable unit (FRU) part number.

After you identify the part number of the part that you want to order, go to Advanced Part Exchange Warranty Service. Registration is required. If you are not able to identify the part number, go to Contacting IBM[®] service and support.

Rack final assembly



P8EIO510-1

Figure 1. Rack final assembly

Table 1. Rack final assembly part numbers

Index number	Part number	Units per assembly	Description
1	45W8836	1	Fixed rail kit - contains left and right fixed rails and attaching screws
2	00E4260	1	Slide rail kit - contains left and right slide rails and attaching screws
3	74Y9063	1	Cable management arm assembly
4	45W8836	1	Fixed rail kit - contains left and right fixed rails and attaching screws
5	00E4260	1	Slide rail kit - contains left and right slide rails and attaching screws
6		1	Electronic Industries Association (EIA) bracket (right side)
7	00E4688	1	Bezel
8		1	EIA bracket (left side)

System parts (air-cooled and water-cooled systems)

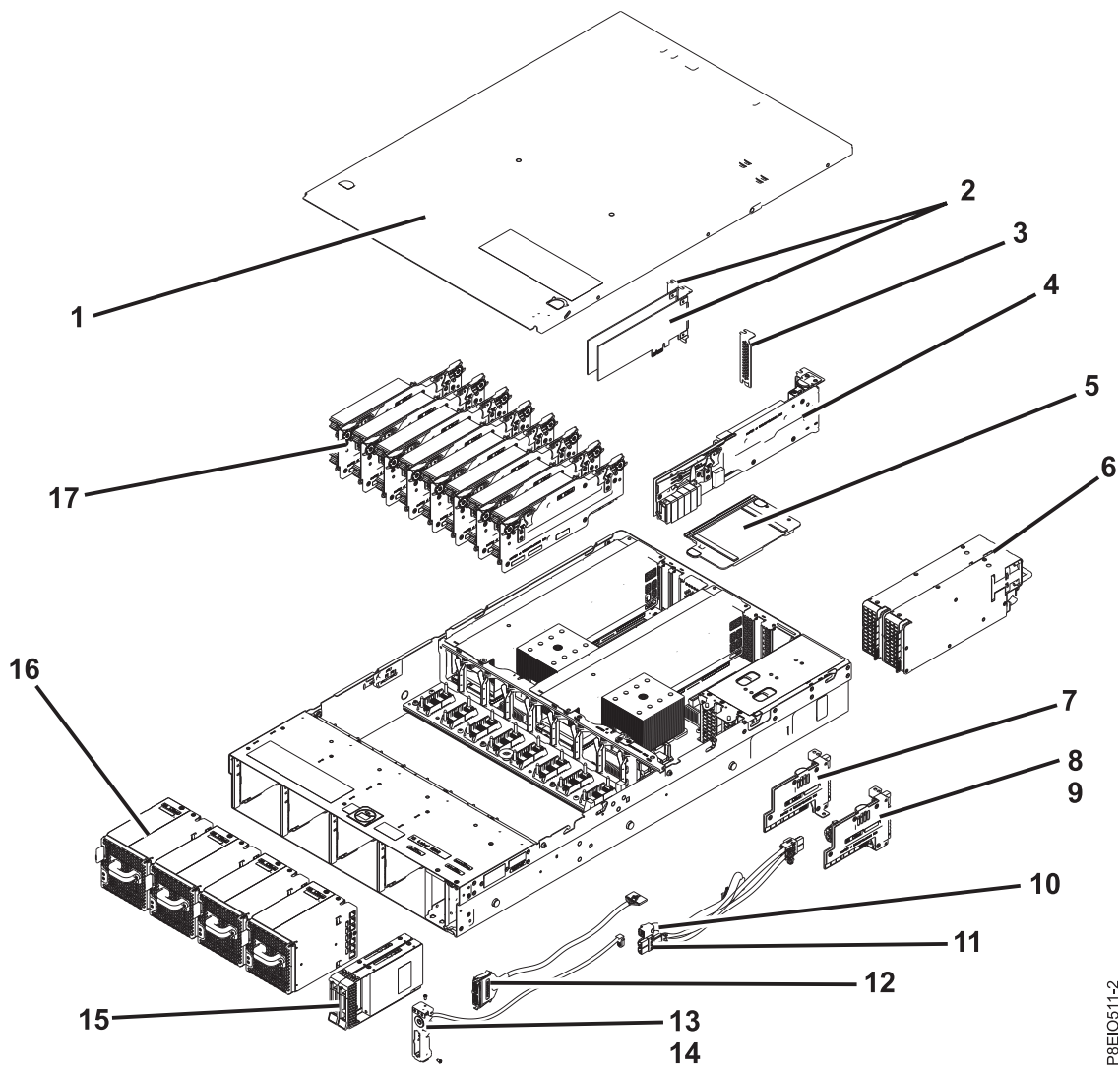


Figure 2. System parts (air-cooled and water-cooled systems)

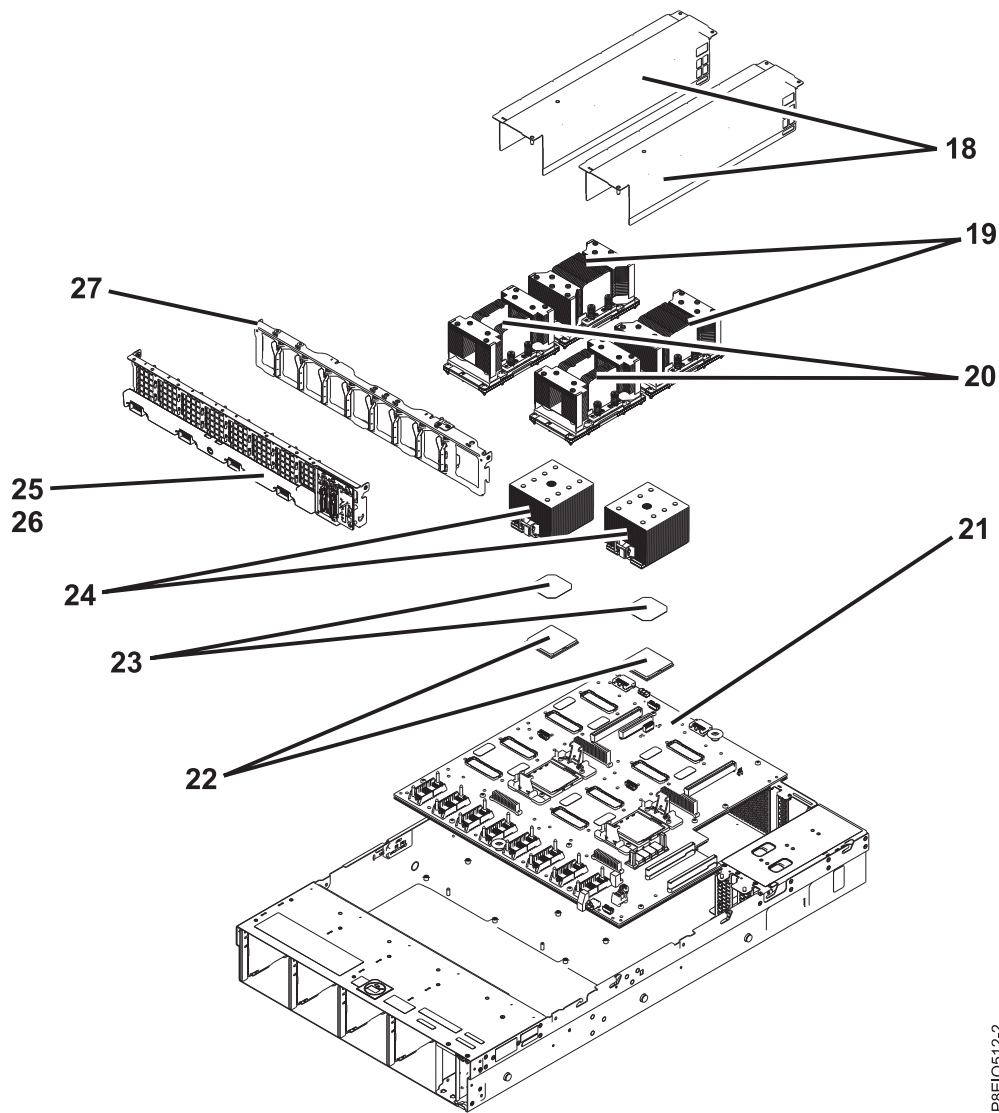
Table 2. System parts (air-cooled and water-cooled systems)

Index number	Part number	Units per assembly	Description
1		1	Top access cover assembly
2		2 - 3	PCI adapters. Use the feature type of the adapter to find the FRU number in PCIe adapters for the 8335-GTB.
3	46K5109	1 - 2	PCI filler
4	00E4574	1	Baseboard management controller (BMC) card
5		1	Power riser air baffle
6	01AF370	2	Power supply
7	00E4705	1	Power riser without time-of-day battery slot

Table 2. System parts (air-cooled and water-cooled systems) (continued)

Index number	Part number	Units per assembly	Description
8	00E4704	1	Power riser with time-of-day battery slot Note: The power riser part number does not include the time-of-day battery. The time-of-day battery is a CR2450N lithium battery.
9		1	Time-of-day battery
10	00E4482	1	Disk and fan signal cable
11	00E4481	1	Fan power cable
12	00E4550	1	Front USB cable with connector
13	00E5189	1	Power switch and power switch cable
14		2	Screw
15	00E4252	2	Drive filler
	00LY266	2	1 TB disk drive
	00LY418	2	2 TB disk drive
	00LY409	2	480 GB solid-state drive
	00LY411	2	960 GB solid-state drive
	00LY423	2	1.9 TB solid-state SATA drive
	00LY438	2	3.84 TB solid-state drive
16	00E4256	4	Fan
17	00E4251	8	Memory riser filler
	00E4498	8	Memory riser
	78P4618	32	4 GB, 1600 MHz DDR4 RDIMM
	78P4620	32	8 GB, 1600 MHz DDR4 RDIMM
	78P4621	32	16 GB, 1600 MHz DDR4 RDIMM
	78P4622	32	32 GB, 1600 MHz DDR4 RDIMM

Additional system parts (air-cooled system)



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Figure 3. Additional system parts (air-cooled system)

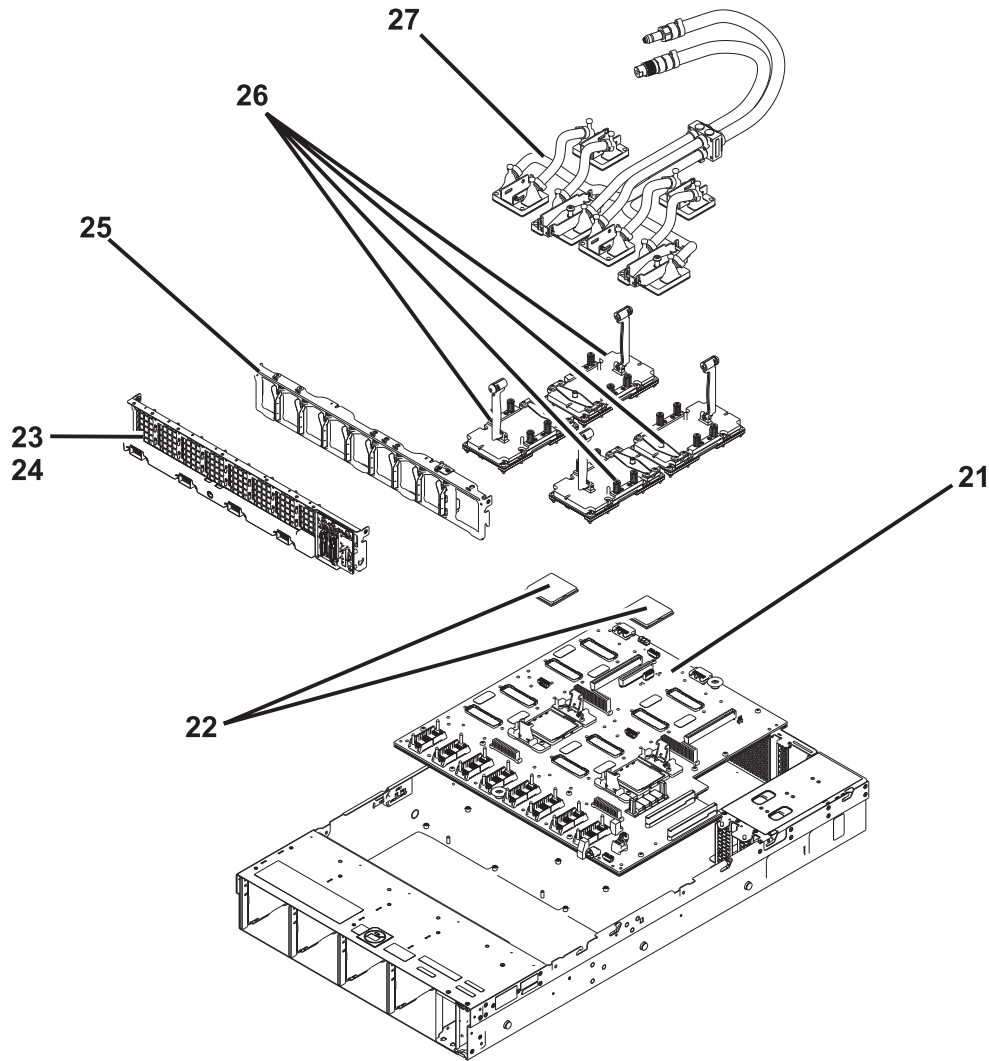
Table 3. Additional system parts (air-cooled system)

Index number	Part number	Units per assembly	Description
18		2	Graphics processing unit (GPU) air baffles
19	01EM024	2	Rear GPU kit (includes GPU card, air baffle, heat sink, and thermal interface material (TIM))
20	01EM025	2	Front GPU kit (includes GPU card, air baffle, heat sink, and TIM)
21	00E4570	1	System backplane kit (includes module removal tool, 4mm hex key, magnetic screwdriver, air pump, and lid removal tool)

Table 3. Additional system parts (air-cooled system) (continued)

Index number	Part number	Units per assembly	Description
22	00E5185	2	8 core 3.259 GHz system processor module kit (includes system processor module, processor tray, 4mm hex driver, module replacement tool, and air pump)
	00E5187	2	10 core 2.860 GHz system processor module kit (includes system processor module, processor tray, 4mm hex driver, module replacement tool, and air pump)
23	01AF286	2	System processor heat sink kit (includes heat sink and TIM)
24	01AF286	2	System processor heat sink kit (includes heat sink and TIM)
25	00E5128	1	Disk drive and fan card
26	00E4476	1	Screw kit Note: The screw kit includes 12 screws for the disk drive and fan card and 16 screws for the system backplane.
27		1	Middle support for the system backplane

Additional system parts (water-cooled system)



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Figure 4. Additional system parts (water-cooled system)

Table 4. Additional system parts (water-cooled system)

Index number	Part number	Units per assembly	Description
21	00E4570	1	System backplane kit (includes module removal tool, 4 mm hex key, magnetic screwdriver, air pump, and lid removal tool) Note: When replacing the system backplane kit in a water-cooled 8335-GTB, you also need the System processor TIM replacement kit (01EM029) and the water-cooled system backplane kit (01EM030) . The water-cooled system backplane kit (01EM030) is not needed if you already have it.

Table 4. Additional system parts (water-cooled system) (continued)

Index number	Part number	Units per assembly	Description
22	00E5185	2	8 core 3.259 GHz system processor module kit (includes system processor module, processor tray, 4mm hex driver, module replacement tool, and air pump)
	00E5187	2	10 core 2.860 GHz system processor module kit (includes system processor module, processor tray, 4mm hex driver, module replacement tool, and air pump)
23	00E5128	1	Disk drive and fan card
24	00E4476	1	Screw kit Note: The screw kit includes 12 screws for the disk drive and fan card and 16 screws for the system backplane.
25		1	Middle support for the system backplane
26	01EM027		Water-cooled GPU kit (includes spreader assembly, GPU card, air baffle, heat sink, and TIM)
27	01AF969	1	Cold plate assembly (includes cold plates, tweezers, and TIMs)

Miscellaneous parts

Table 5. Miscellaneous system parts

Description	Part number	Units per assembly
System processor TIM replacement kit (includes TIM removal tool, tweezers, and TIM)	01EM029	1
Water-cooled system backplane kit (includes cold plate and module tray)	01EM030	1

Rear ports

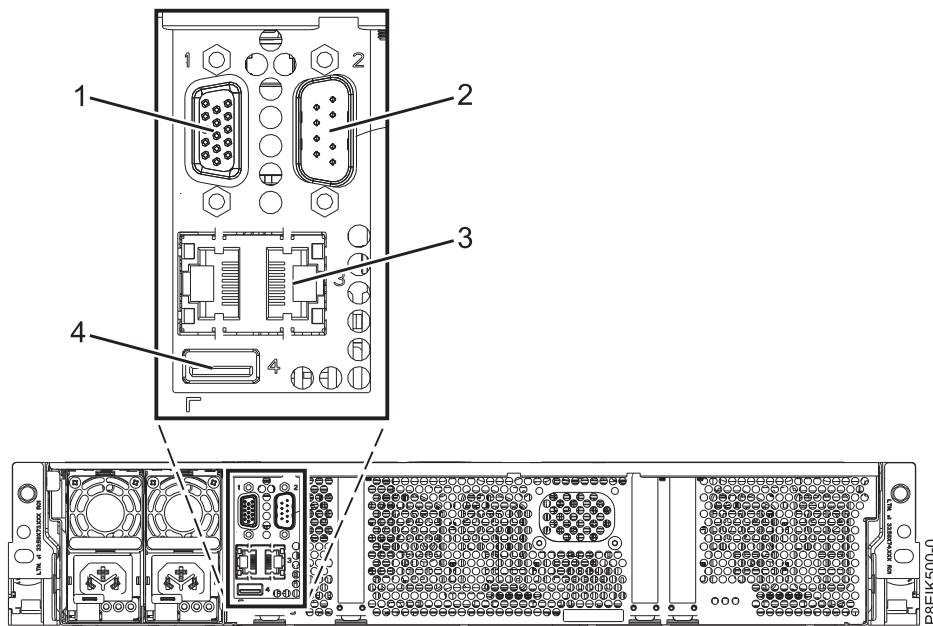


Figure 5. Rear view of the system with ports displayed

Table 6. Port descriptions

Identifier	Description
1	Video Graphics Array (VGA). Text based capability is only supported at this time.
2	Intelligent Platform Management Interface (IPMI) serial
3	Ethernet. Use the left Ethernet port for the BMC/IPMI interface (as eth0). Use the right Ethernet port for any direct OS usage (as eth1).
4	USB 3.0

Installing and removing IBM Power System S822LC (8335-GTB) parts

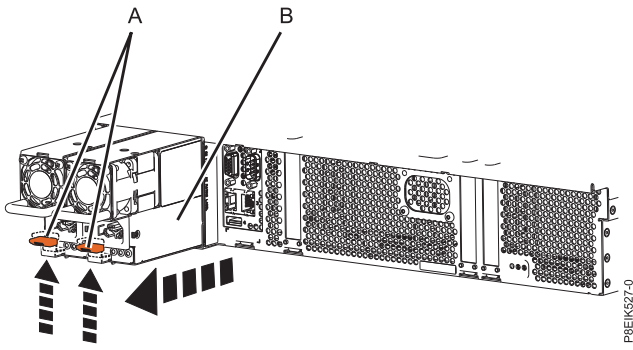


Figure 6. Removing a power supply from the system

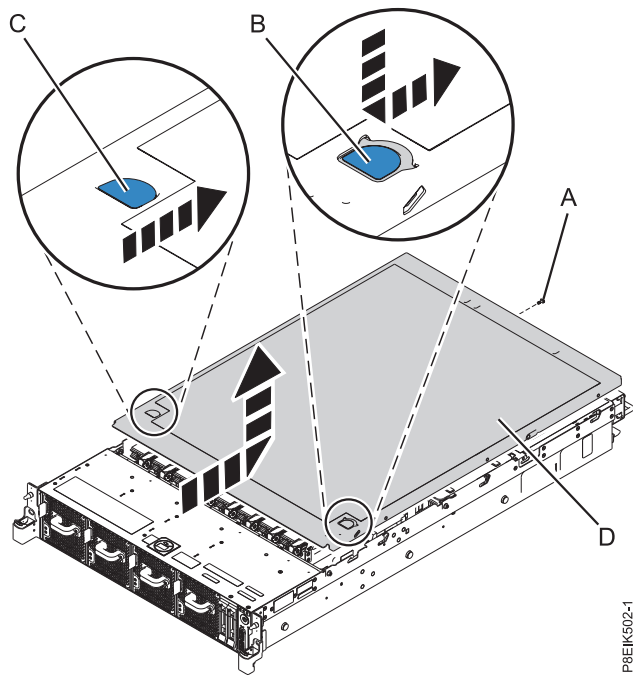


Figure 7. Removing the cover

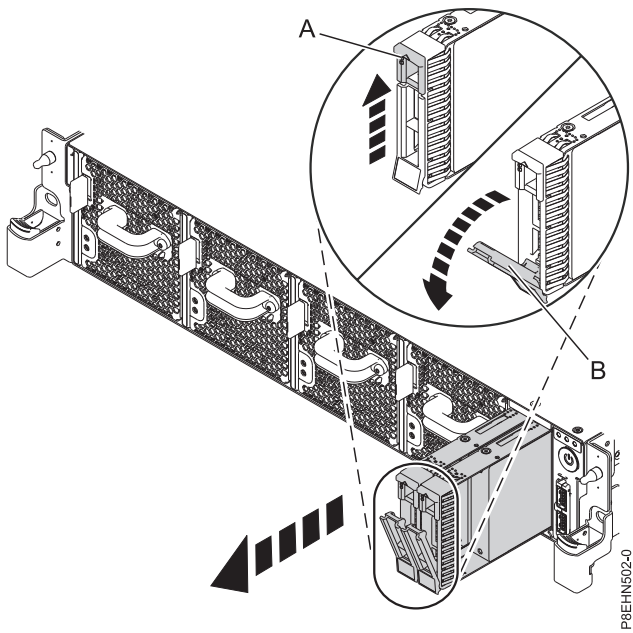


Figure 8. Disk drive lock detail

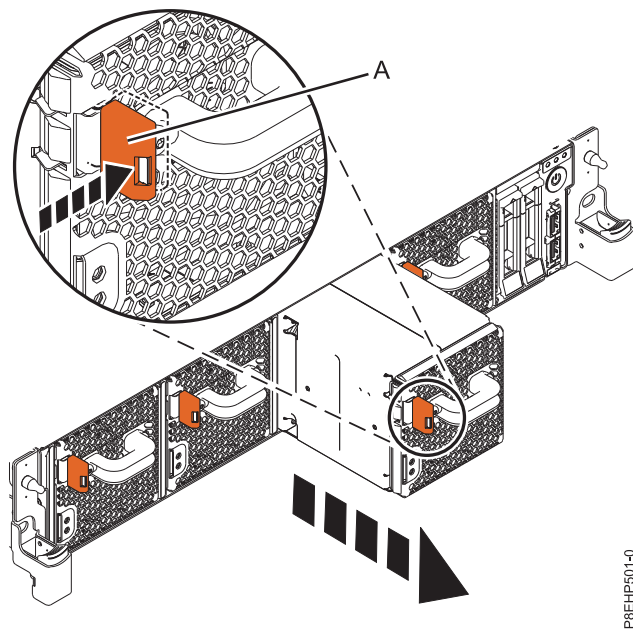


Figure 9. Removing a fan from the system

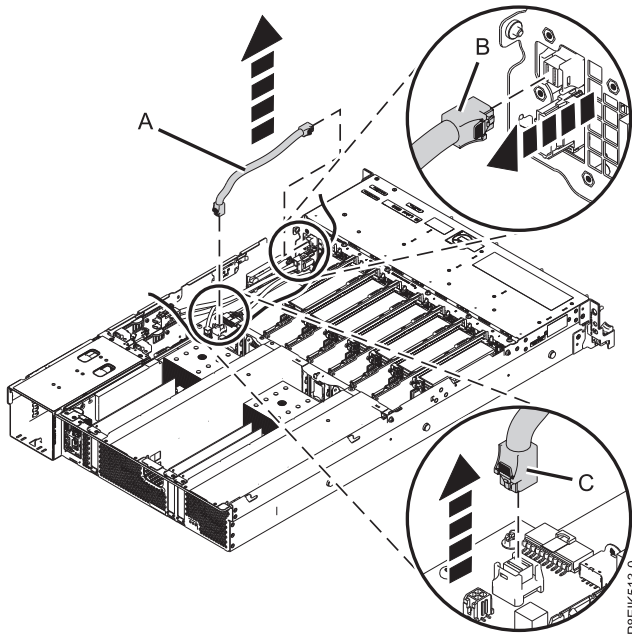


Figure 10. Removing the disk and fan signal cable

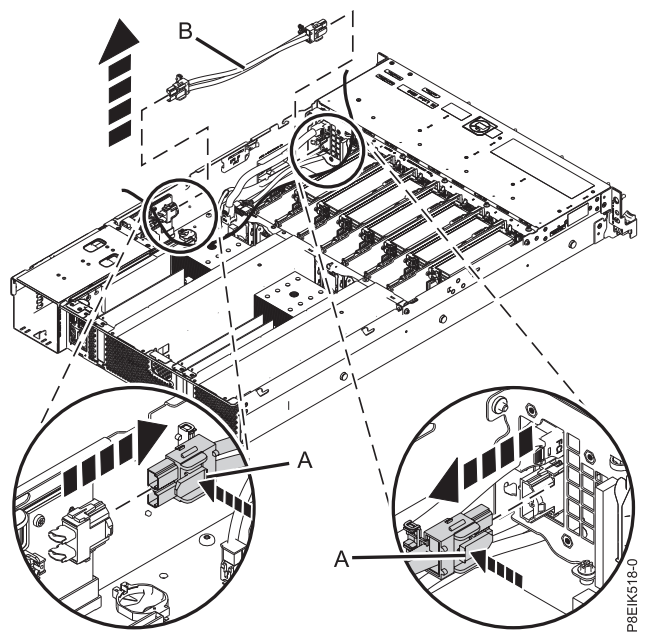


Figure 11. Removing the fan power cable from the system

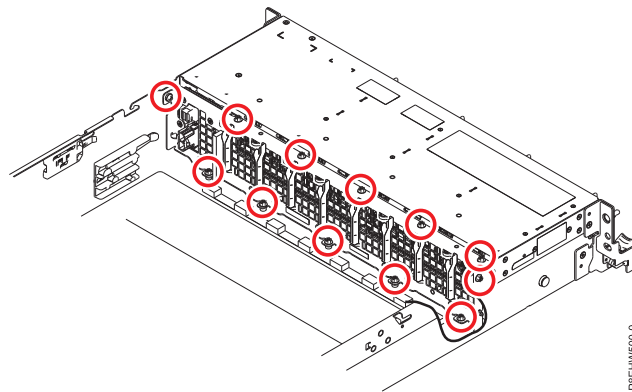


Figure 12. Screw locations for the disk drive and fan card

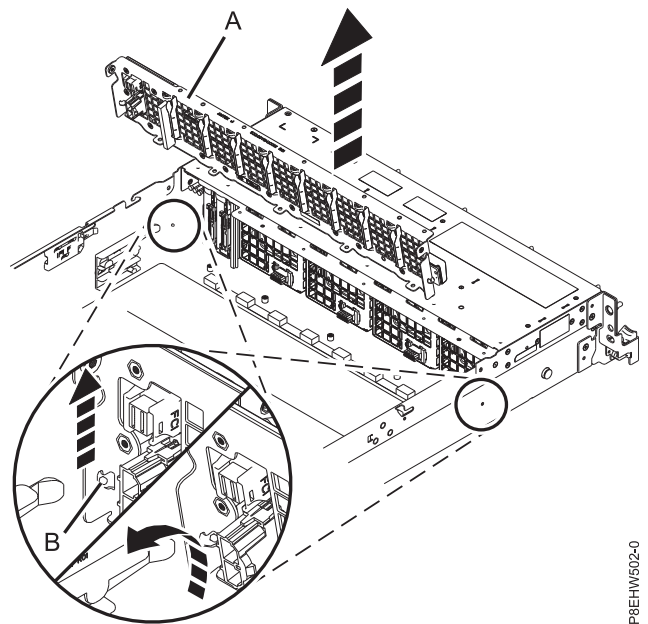
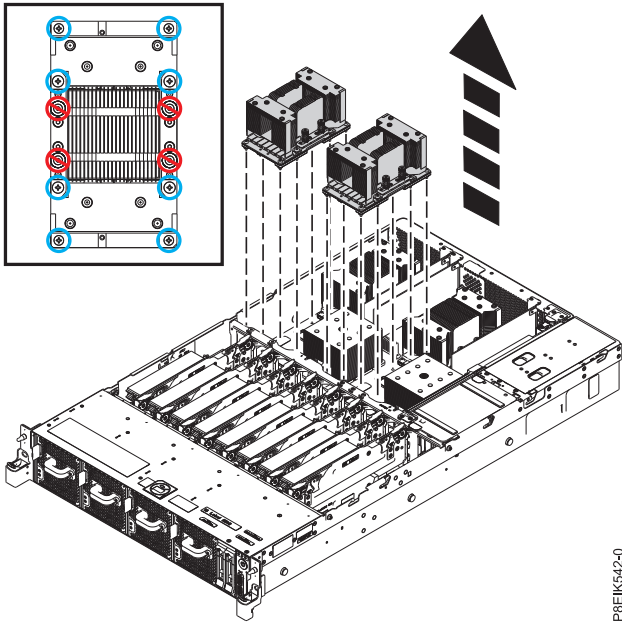
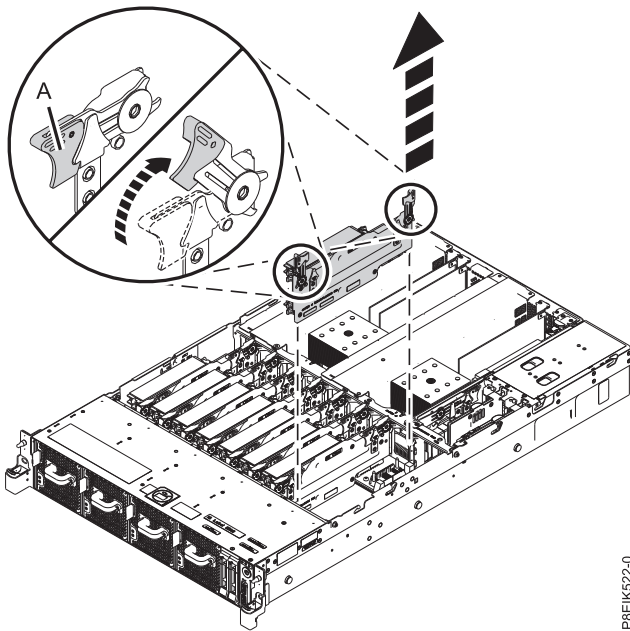


Figure 13. Removing the disk drive and fan card



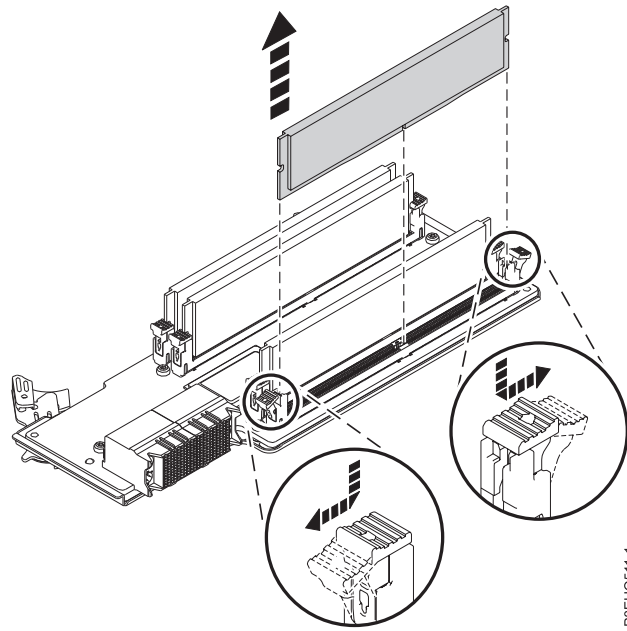
P8EIK542-0

Figure 14. Remove eight GPU screws per GPU; do not loosen the four spring-loaded screws



P8EIK522-0

Figure 15. Removing a memory riser from the system



P8EHC511-1

Figure 16. Removing memory DIMM from a slot on the riser

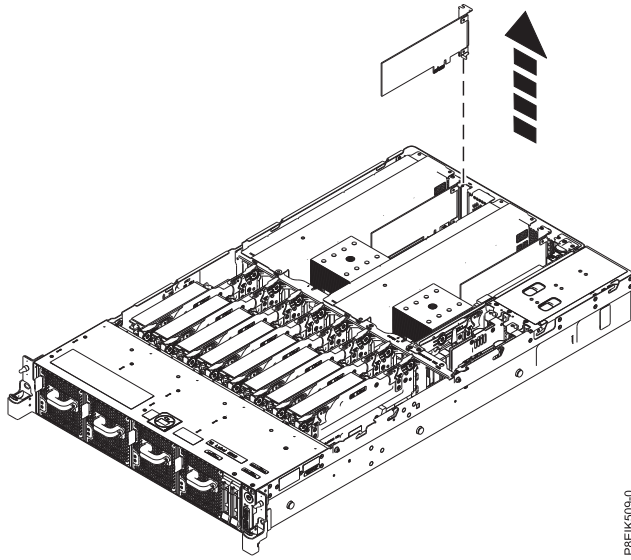


Figure 17. Removing a PCIe adapter

P8EIK509-0

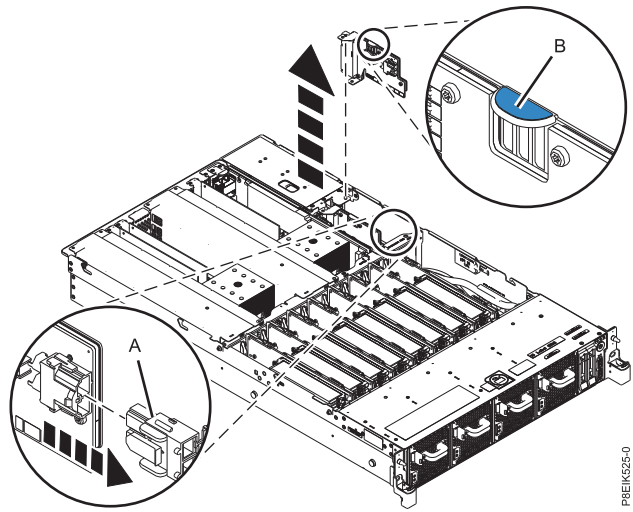


Figure 18. Removing a power riser from the system

P8EIK525-0

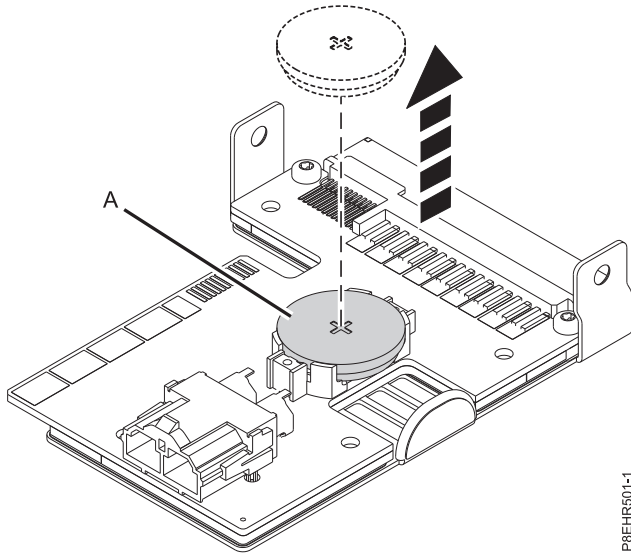


Figure 19. Removing the time-of-day battery from the power riser

P8EHR501-1

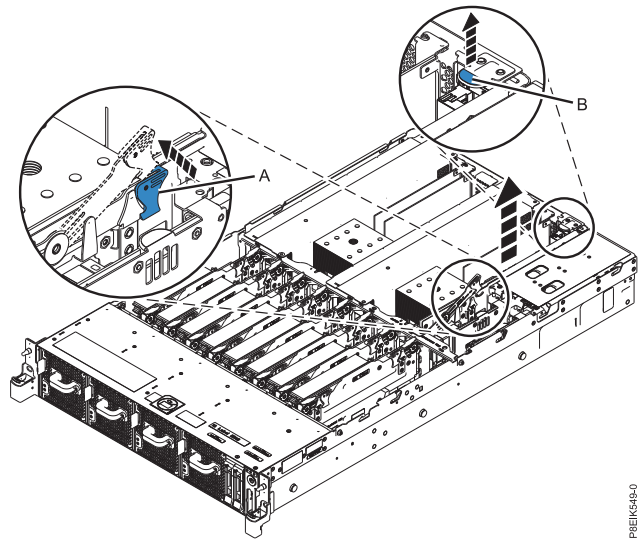


Figure 20. Removing the BMC card

P8EIK548-0

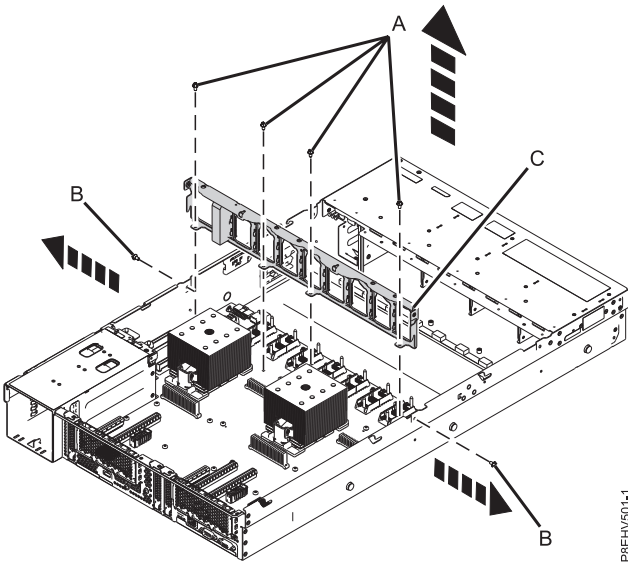
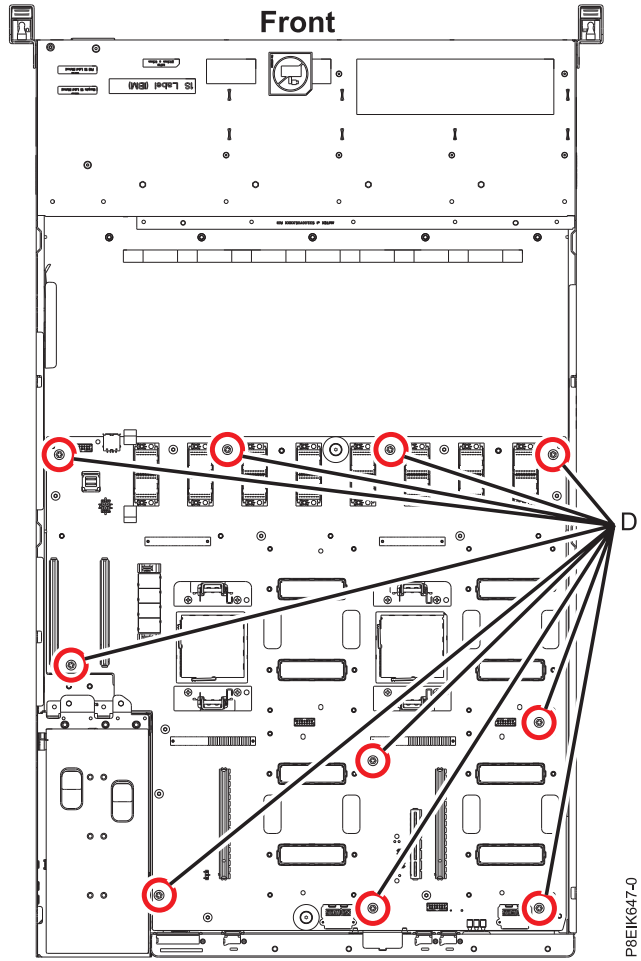


Figure 21. Remove the middle support and screw locations

P8EHV501-1



P8EIK647-0

Figure 22. System backplane screw locations

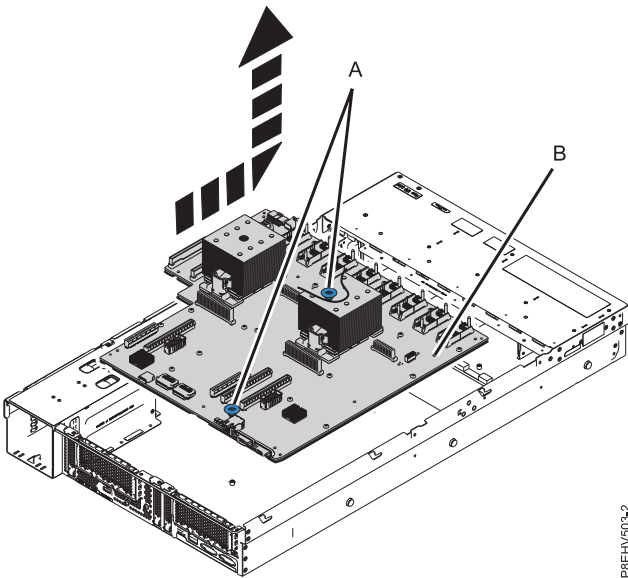


Figure 23. Lifting out the system backplane

P8EHV503-2

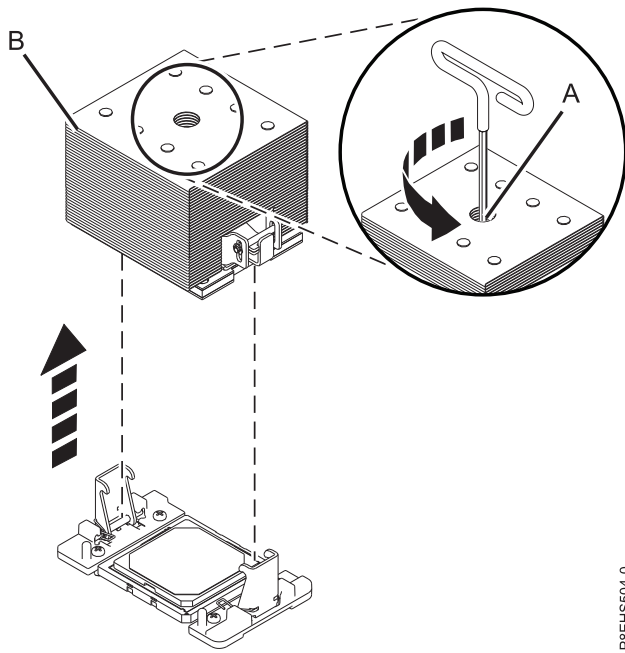


Figure 24. Removing the heat sink

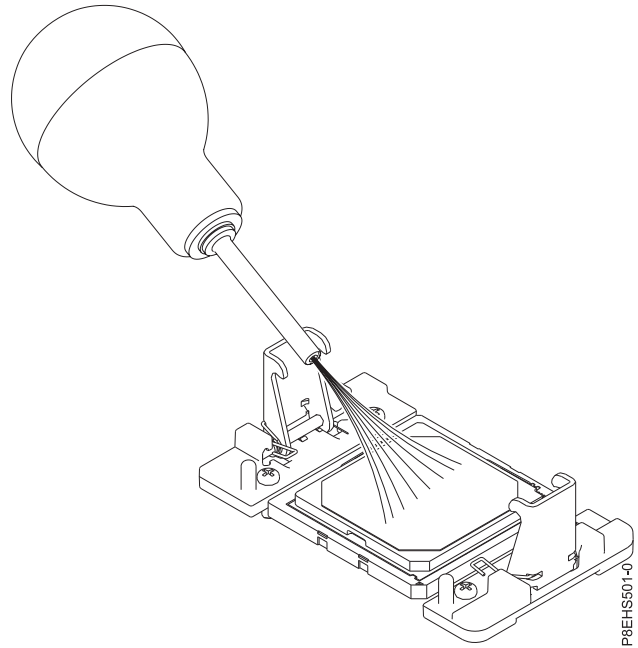


Figure 25. Removing dust and debris from the system processor module area

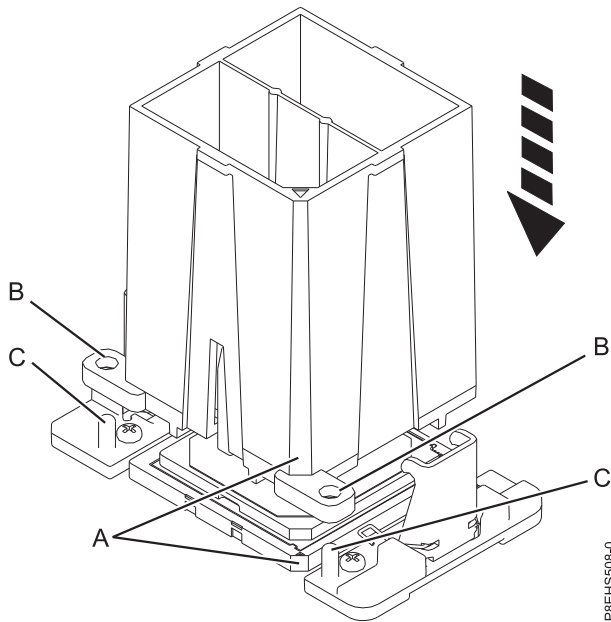


Figure 26. Lowering the removal tool onto the system processor module

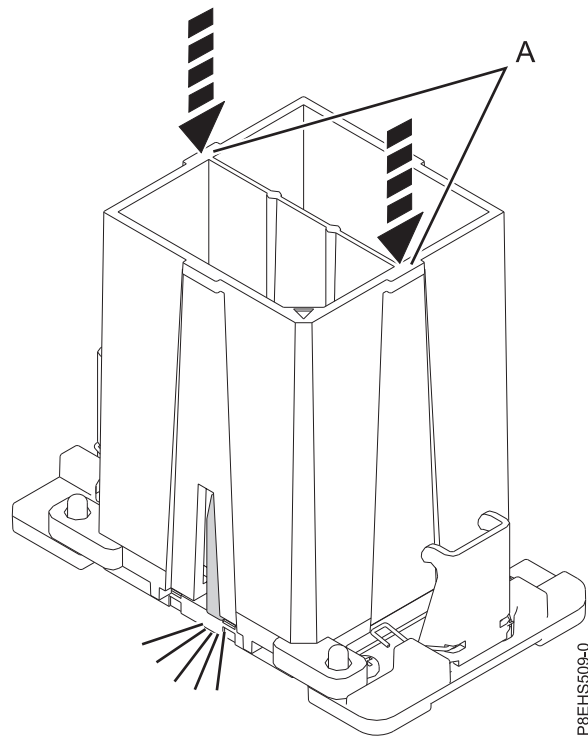
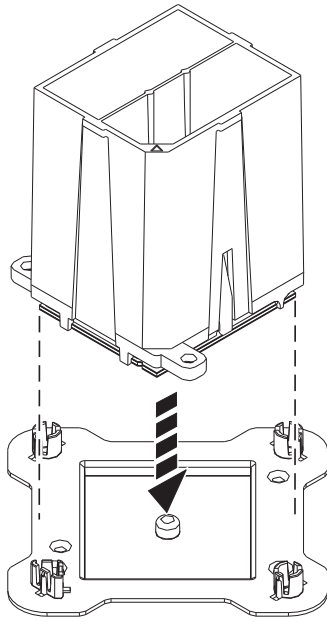
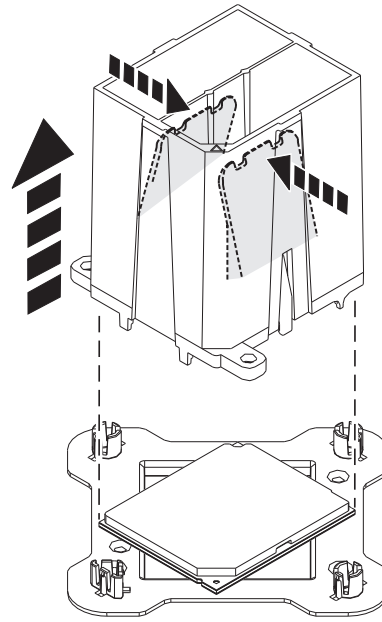


Figure 27. Locking the system processor module into the tool



P8EDE521-1

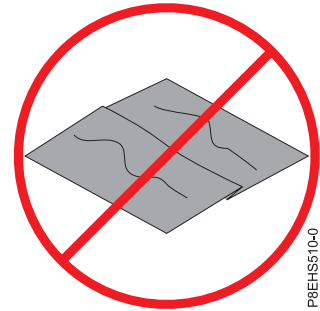
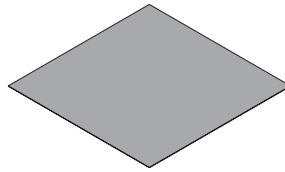
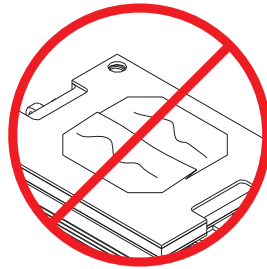


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Figure 28. Placing the tool at an angle on the top cover of the packaging

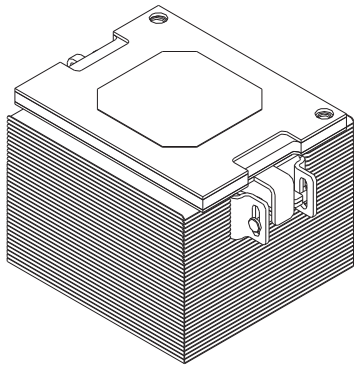
Figure 29. Releasing the system processor module from the tool

If the thermal interface material is damaged, replace it.



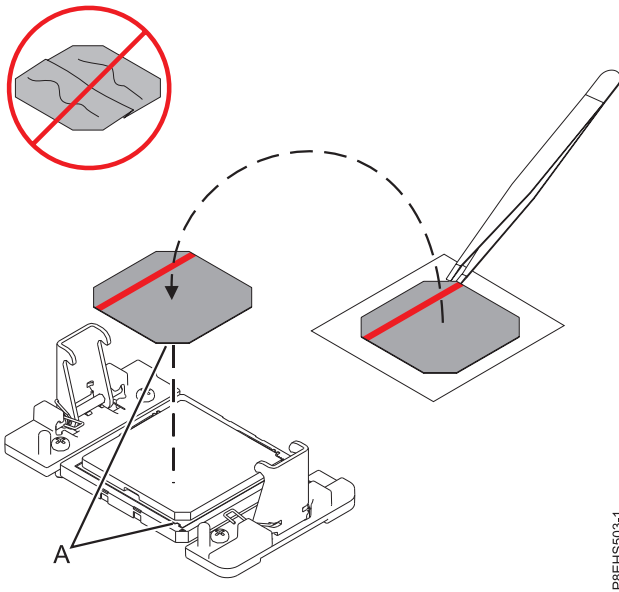
P8EHS510-0

Figure 31. Inspecting the gray-colored thermal interface material



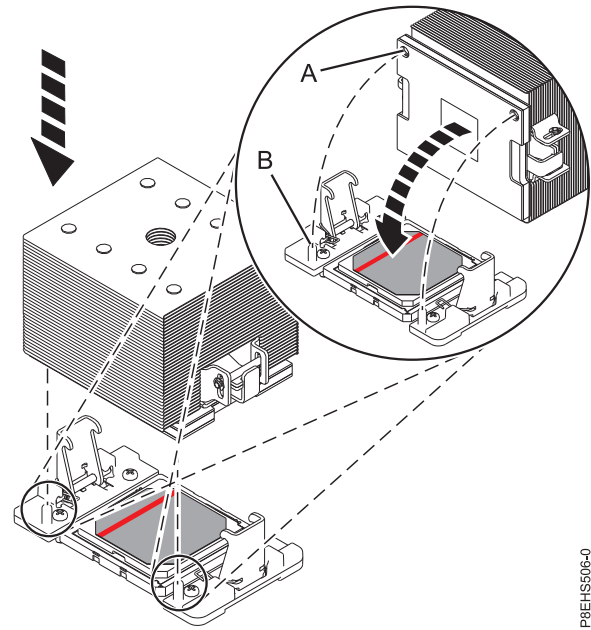
P8EHS502-0

Figure 30. Inspecting the silver-colored thermal interface material



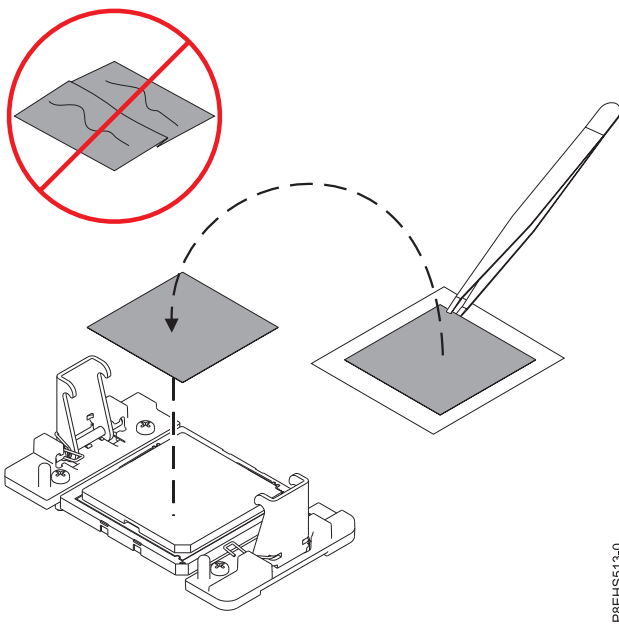
P8EH5003-1

Figure 32. Installing the silver-colored TIM onto the processor



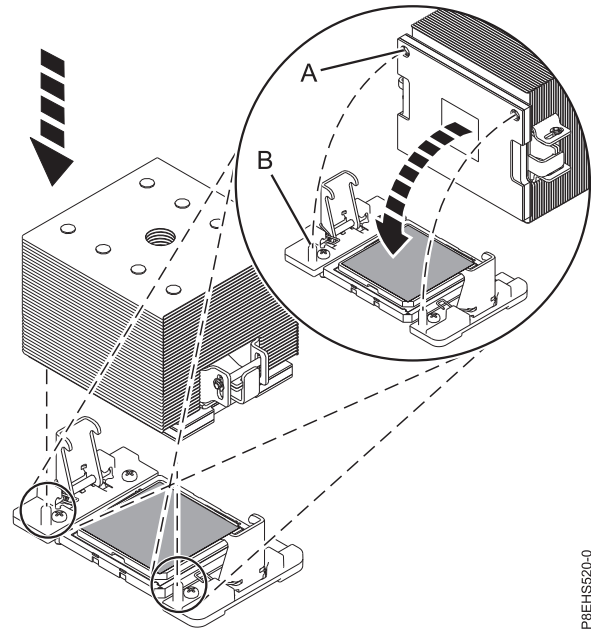
P8EH5006-0

Figure 33. Installing the new heat sink on the silver-colored TIM



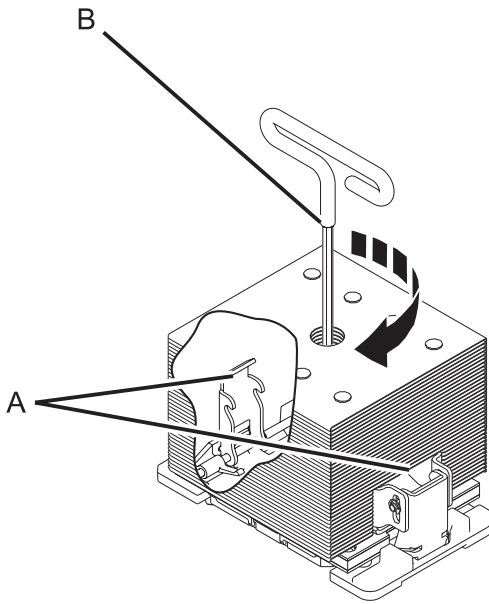
P8EH5113-0

Figure 34. Installing a new gray-colored TIM onto the processor



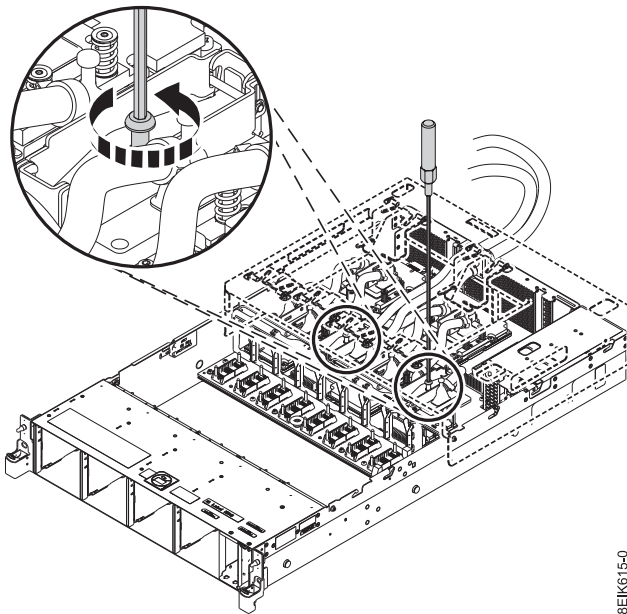
P8EH520-0

Figure 35. Installing the heat sink on the gray-colored TIM



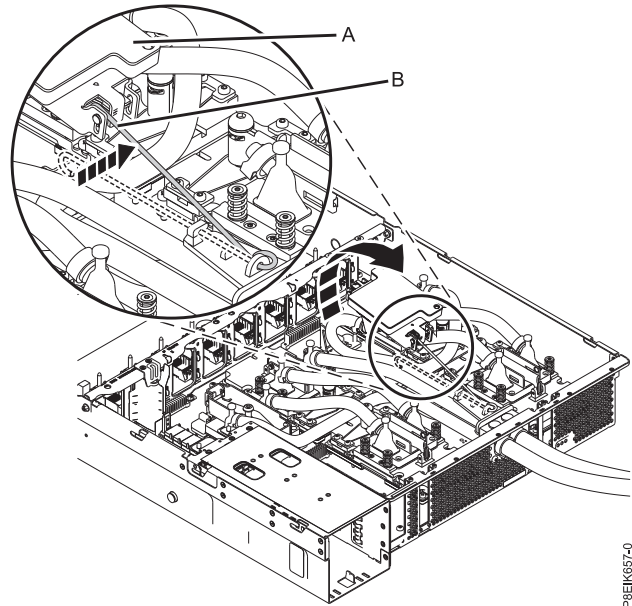
P8EHS507-0

Figure 36. Tightening the center load screw on the heat sink



P8EIK615-0

Figure 37. Loosening the cold plate retainer screw



P8EIK657-0

Figure 38. Removing the cold plate

This October 24, 2017 edition applies to IBM Power Systems servers that contain the POWER8 processor and to all associated models.

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